



HTIP125

PNP EPITAXIAL PLANAR TRANSISTOR

Description

The HTIP125 is designed for medium power linear and switching applications.

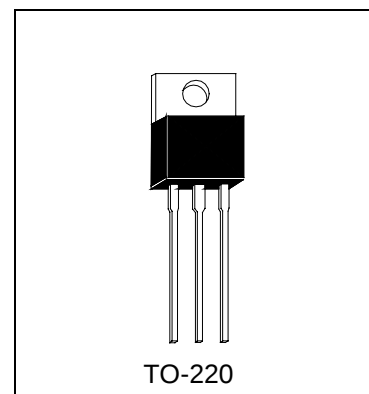
Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$)

- Maximum Temperatures
Storage Temperature $-55 \sim +150^{\circ}\text{C}$
Junction Temperature $+150^{\circ}\text{C}$ Maximum
- Maximum Power Dissipation
Total Power Dissipation ($T_C=25^{\circ}\text{C}$) 65 W
Total Power Dissipation ($T_A=25^{\circ}\text{C}$) 2 W
- Maximum Voltages and Currents
 BV_{CBO} Collector to Base Voltage -60 V
 BV_{CEO} Collector to Emitter Voltage -60 V
 BV_{EBO} Emitter to Base Voltage -5 V
 I_C Collector Current -5 A

Electrical Characteristics ($T_A=25^{\circ}\text{C}$)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV_{CBO}	-60	-	-	V	$I_C=-1\text{mA}$, $I_E=0$
I_{CEO}	-	-	-0.5	mA	$V_{CE}=-30\text{V}$, $I_E=0$
I_{CBO}	-	-	-0.2	mA	$V_{CE}=-60\text{V}$, $I_B=0$
I_{EBO}	-	-	-2	mA	$V_{EB}=-5\text{V}$, $I_C=0$
$*V_{CE(sat)1}$	-	-	-2	V	$I_C=-3\text{A}$, $I_B=-12\text{mA}$
$*V_{CE(sat)2}$	-	-	-4	V	$I_C=-5\text{A}$, $I_B=-20\text{mA}$
$*V_{BE(on)}$	-	-	-2.5	V	$I_C=-3\text{A}$, $V_{CE}=-3\text{V}$
$*h_{FE1}$	1000	-	-		$I_C=-0.5\text{A}$, $V_{CE}=-3\text{V}$
$*h_{FE2}$	1000	-	-		$I_C=-3\text{A}$, $V_{CE}=-3\text{V}$
Cob	-	-	300	FP	$V_{CB}=-10\text{V}$, $f=0.1\text{MHz}$, $I_E=0$

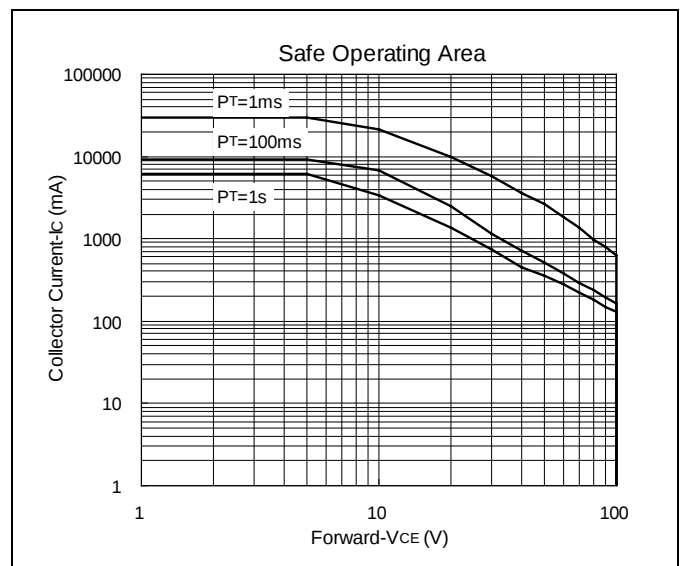
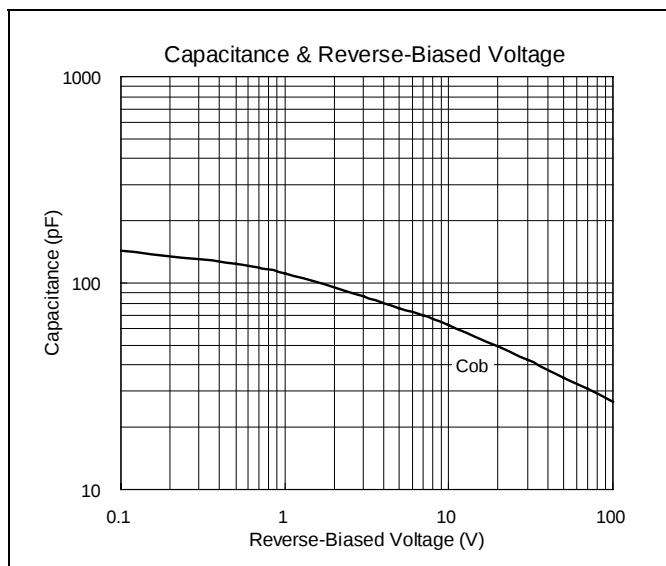
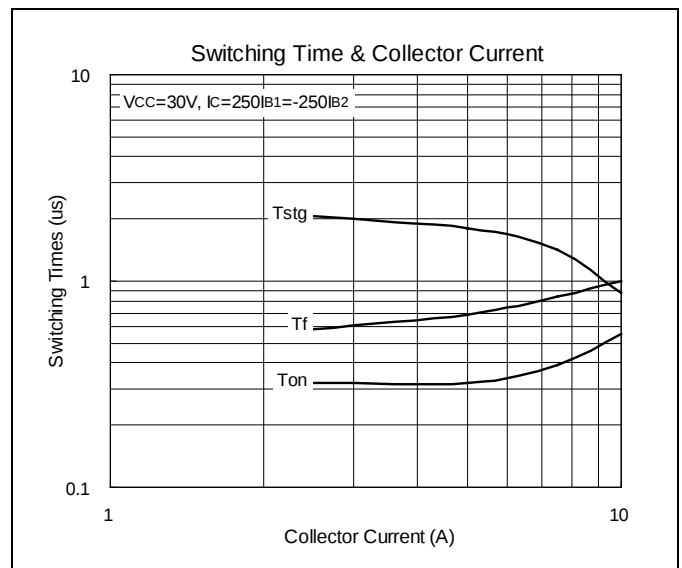
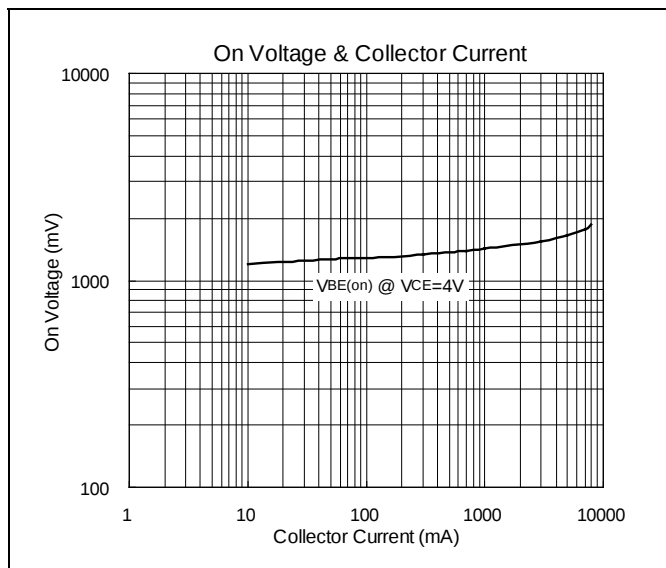
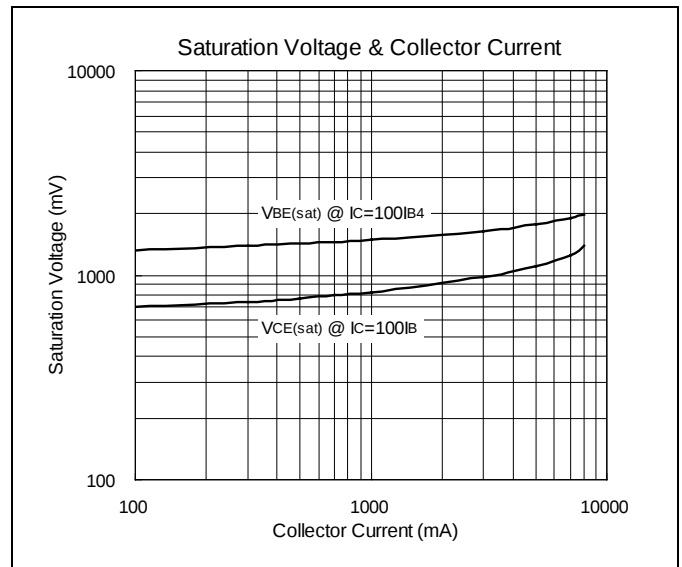
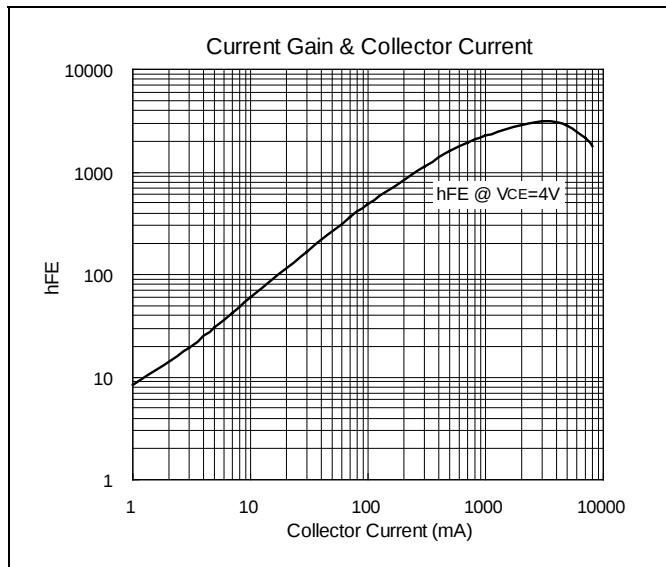
*Pulse Test: Pulse Width $\leq 380\mu\text{s}$, Duty Cycle $\leq 2\%$



TO-220

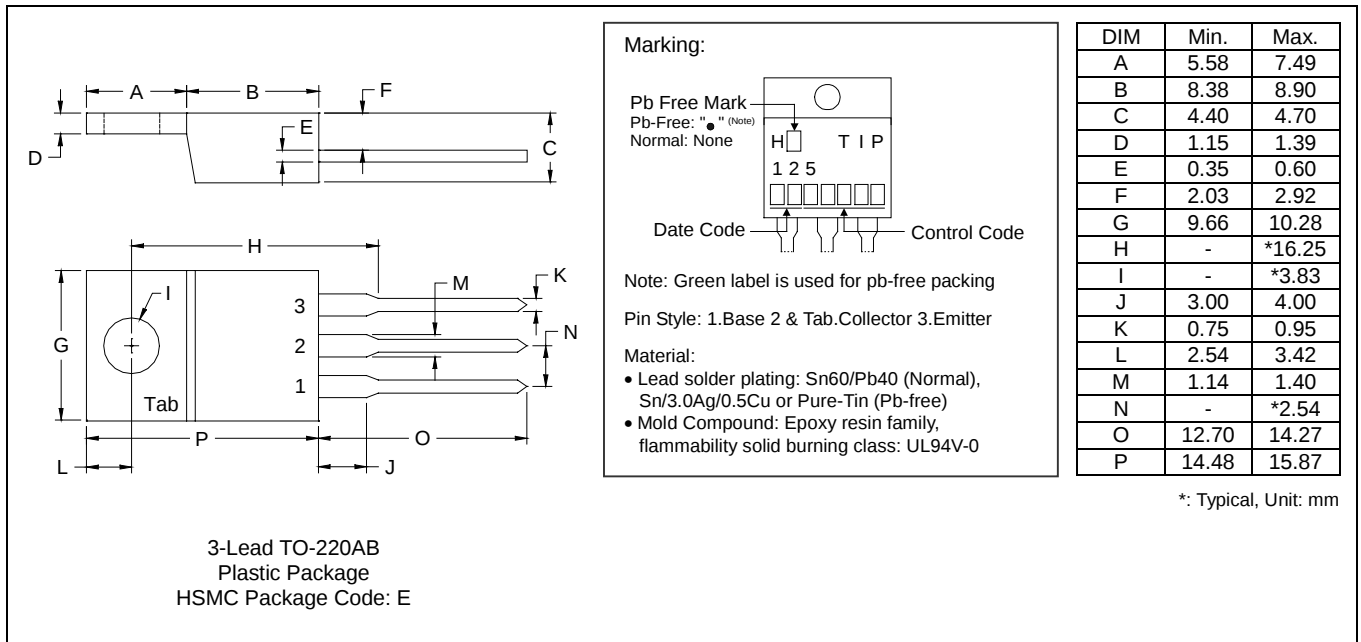


Characteristics Curve





TO-220AB Dimension



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Head Office And Factory:

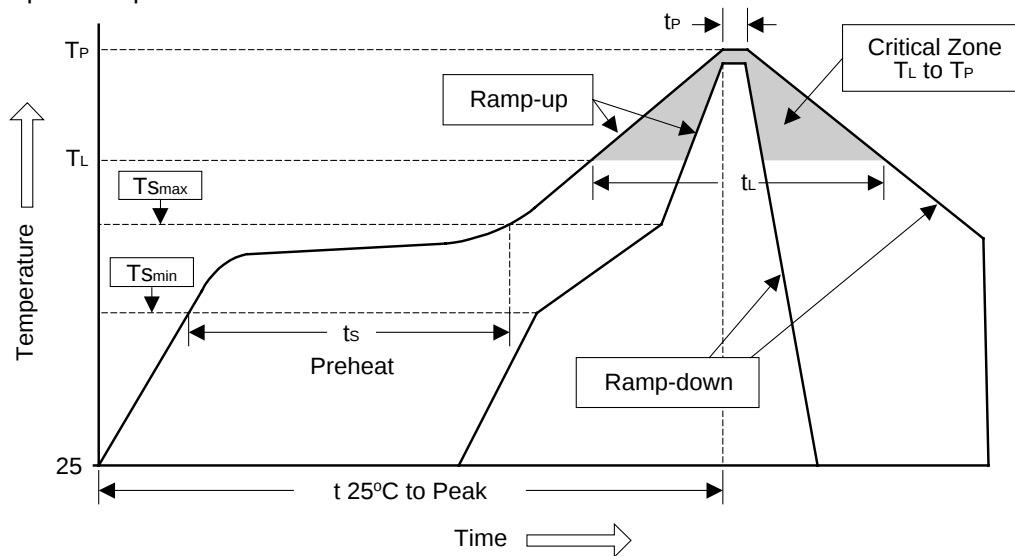
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Soldering Methods for HSMC's Products

1. Storage environment: Temperature=10°C~35°C Humidity=65%±15%
2. Reflow soldering of surface-mount devices

Figure 1: Temperature profile



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	<3°C/sec	<3°C/sec
Preheat		
- Temperature Min (T_{smin})	100°C	150°C
- Temperature Max (T_{smax})	150°C	200°C
- Time (min to max) (t_s)	60~120 sec	60~180 sec
T_{smax} to T_L		
- Ramp-up Rate	<3°C/sec	<3°C/sec
Time maintained above:		
- Temperature (T_L)	183°C	217°C
- Time (t_L)	60~150 sec	60~150 sec
Peak Temperature (T_P)	240°C +0/-5°C	260°C +0/-5°C
Time within 5°C of actual Peak Temperature (t_P)	10~30 sec	20~40 sec
Ramp-down Rate	<6°C/sec	<6°C/sec
Time 25°C to Peak Temperature	<6 minutes	<8 minutes

3. Flow (wave) soldering (solder dipping)

Products	Peak temperature	Dipping time
Pb devices.	245°C ±5°C	5sec ±1sec
Pb-Free devices.	260°C +0/-5°C	5sec ±1sec